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(54) Title: DIE PACKAGE AND METHOD FOR MANUFACTURING THE DIE PACKAGE

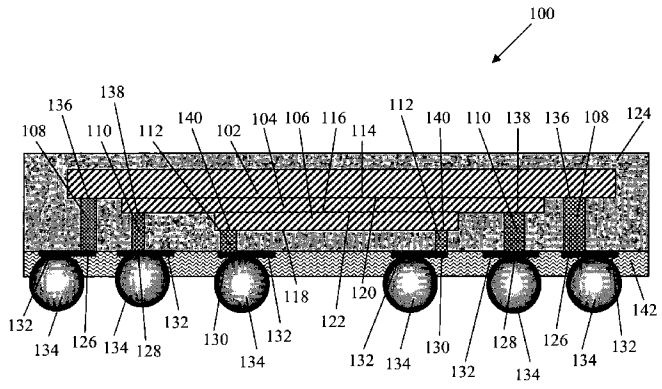


Figure 1

(57) Abstract: A die package and a method for manufacturing the die package are provided. The die package includes a second die arranged above a first die, the first die comprising an interconnect region on a surface facing the second die, wherein the second die is arranged laterally next to the interconnect region of the first die; a first package-internal free-standing interconnect structure disposed above the interconnect region of the first die; a second package-internal free-standing interconnect structure disposed above an interconnect region of the second die, the interconnect region of the second die being on a surface of the second die facing away from the first die; and package material formed partially around the first package-internal free-standing interconnect structure and the second package-internal free-standing interconnect structure such that a connecting portion of the first package-internal free-standing interconnect structure and a connecting portion of the second package-internal free-standing interconnect structure remains uncovered to be electrically connected to a package-external interconnect structure.

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